CLAIMS

1. An aramid epoxy resin glue, based on mass percentage of raw materials, comprising:

90-94 parts by weight of an epoxy resin;

3.5-7.5 parts by weight of silicon dioxide;

0-10 parts by weight of a foamed filler; and

0.3-0.5 parts by weight of an aramid 1313 reticular fiber;

wherein the aramid 1313 reticular fiber has a fineness of 1-2 D; and

microscopically, the aramid 1313 reticular fiber has a microscopic three-dimensional reticular structure formed by mutual cross-linking of filaments, strips and films; wherein

the filaments have a diameter of 10-500 nm;

the strips have a diameter of 0.5-20 μm; and

the films have a diameter of 5-50 μm.

2. The aramid epoxy resin glue according to claim 1, wherein the epoxy resin includes a flame-retardant epoxy resin;

the aramid 1313 reticular fiber has a length of 1-7 mm;

the aramid 1313 reticular fiber has an aspect ratio of (50-1000): 1;

the silicon dioxide includes a fumed silica powder;

the foamed filler includes a hollow glass microsphere;

the aramid epoxy resin glue includes one or more of an aramid epoxy resin edge-sealing glue, an aramid epoxy resin filling glue and an aramid epoxy resin molding glue;

in the aramid epoxy resin edge-sealing glue or the aramid epoxy resin filling glue, the silicon dioxide is present in an amount of 3.5-5.7 parts by weight, based on mass percentage of raw materials; and

in the aramid epoxy resin molding glue, the silicon dioxide is present in an amount of 5.7-7.5 parts by weight, based on mass percentage of raw materials.

3. The aramid epoxy resin glue according to claim 2, wherein the silicon dioxide has a particle size of 12 nm-6 μm;

the aramid epoxy resin edge-sealing glue has a density of 0.6-1.0 g/cm^3;

the aramid epoxy resin edge-sealing glue is used for edge banding of a lightweight honeycomb composite material;

the aramid epoxy resin filling glue has a density of 1.4-1.6 g/cm^3;

the aramid epoxy resin filling glue is used for bonding hardware on a resin composite material;

the aramid epoxy resin molding glue has a density of 0.9-1.6 g/cm^3;

the aramid epoxy resin molding glue is dough-like before curing; and

the aramid epoxy resin molding glue is used for modeling on a resin composite material.

4. A method for preparing the aramid epoxy resin glue according to any one of claims 1-3, comprising the following step:

a) mixing an aramid 1313 reticular fiber, an epoxy resin and silicon dioxide, to obtain an aramid epoxy resin glue.

5. The method according to claim 4, wherein in step a), a foamed filler is further included;

the mixing is performed for a duration of 10-30 min;

the aramid epoxy resin glue is added with a curing aid before use;

the curing aid includes a modified amine curing agent, an accelerating agent and a coupling agent;

the aramid epoxy resin glue and the curing aid have a mass ratio of 4: 1; and

the aramid epoxy resin glue has an open time of 30-40 min.

6. An aramid paper honeycomb composite part, comprising prepreg cured sheets, an aramid paper honeycomb core and a Honeycon glue; wherein

the aramid paper honeycomb core is compounded between the prepreg cured sheets, forming a sandwich structure;

the Honeycon glue includes a Honeycon bonding glue;

the Honeycon bonding glue is bonded between the aramid paper honeycomb core and the prepreg cured sheets; and

the Honeycon glue is the aramid epoxy resin glue according to any one of claims 1-3 or the aramid epoxy resin glue prepared using the method according to any one of claims 4-5.